Form PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. 30-5000-(4015) Div. 2

PRIORITY SERIAL NO. 09/449,025

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3	AG Electromigration Properties of Copper-Zirc 2745-2750. AH Directional and Preferential Sputtering-Bas								t. 1998,
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	AK	Preparation of L 1951, p. 185-208		Cu-1 at. %Cr Thin Films by Magn	etron, C. Cabral, Jr., e	et al., <i>Journa</i>	al of the Insti	sute of Metals	, June
7	AK AL	1951, p. 185-208	tical Tables of	Numerical Data, Physics, Chemistr					

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Sheet 1 of 1

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

SERIAL NO. 09/784,233 ATTY. DOCKET NO. 30-5000-(4015)-Div2 APPLICANT

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ΙT Shozo Nagano et al.

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	AB	3,923,675	12/02/75	Mazdiyasni et al.		252	62.9		
	AC	5,086,617	11/19/91	Tanemoto et al.		501	134		
7	AD	5,314,651	05/24/94	Kulwicki		264	65		
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1		pp. 251-25			,				
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		pp. 584-56	7 (1970).						
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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. 30-5000-(4015)-Div2 SERIAL NO. 09/784,233

LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)

APPLICANT Shozo Nagano et al.

February 14, 2001

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(2	44	3,963,934	06/15/76	Ormrod		250	499		
	AB	4,132,614	01/02/79	Cuomo et a	1.	204	192 EC		
	AC	4,149,907	04/17/79	Wronski et	al.	148	1.5		
	AD	4,159,909	07/03/79	Wilson		75	170		
	AE	4,198,283	04/15/80	Class et al		204	298		
	AF	4,209,375	06/24/80	Gates et al		204	192 R		
	AG	4,395,979	05/31/83	Pierce et a		204	298		
	АН	4,545,882	10/08/85	McKelvey		204	192 R		
	Al	4,629,859	12/16/96	Reddy		219	121 LM		
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1	AK	5,171,411	12/15/92	Hillendahl e	t al.	204	192.12	_	
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63	AL	EP 0 882 813 A1	09.12.98	Europe (Tai	ahashi)				
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12	AP	63033174 0.	12.02.88	Japan (Kez	ıka) - Abstract only				
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R	AR	Dierckxsens et al.,	Effect of trace	elements on	he recrystallization behavior of high purity	ox ygen-c ontaini	ing copper, ER	ZMETAL 28(11).	
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12		(1996). Fu	Il text of articl	e submitted in	abstract earlier.				
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7	AA	5,215,639	06/01/93	Boys		204	192.12		
	AB	5,242,566	09/07/93	Parker		204	298.2		
	AC	5,268,236	12/07/93	Dumont et al.		428	636		
	AD	5,282,943	02/01/94	Lannutti et af.		204	192.12		
	AE	5,282,946	02/01/94	Kinoshita et al.		204	298.13		
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	AG	5,397,050	03/14/95	Mueller .	•	228	193		
	АН	5,490,914	02/13/96	Hurwitt et al.		204	289.12		
	AI	5,589,040	12/31/96	Nishimura		204	192.26		
	AJ	5,674,367	10/07/97	Hunt et al.		204	298.12		
1	AK	5,693,203	12/02/97	Ohhashi et al.		240	298.12		
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